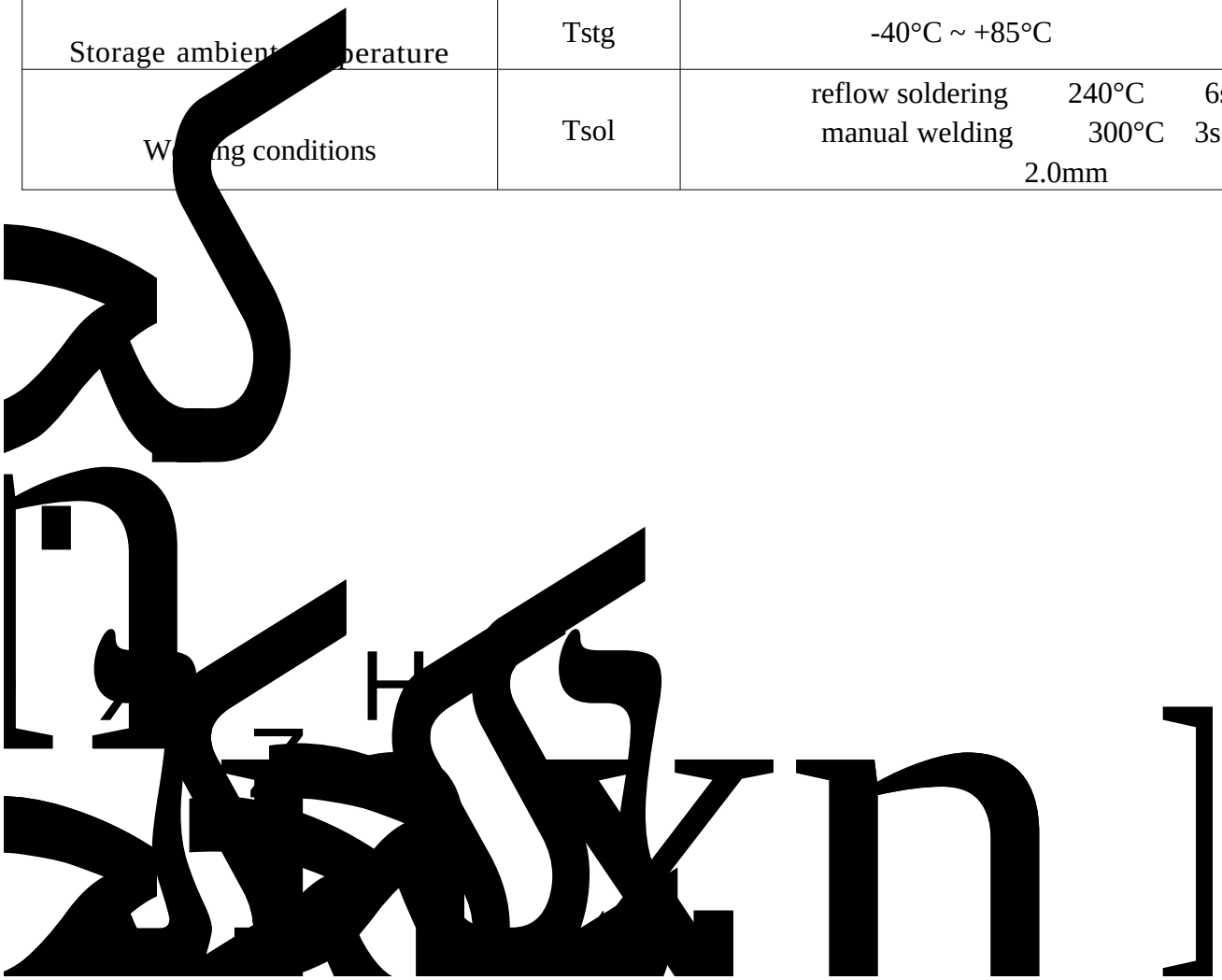
目录

Catalogue

电性参数

Consumed power	Pd	70	mW
Max Continuous Forward Current	IF	20	mA
Peak Forward Current	IFp	80	mA
Operating ambient temperature	Topr	-20°C ~ +85°C	
Storage ambient temperature	Tstg	-40°C ~ +85°C	
Welding conditions	Tsol	reflow soldering 240°C 6s manual welding 300°C 3s 2.0mm	



亮度分档

：

代码	最小值	最大值	单位	测试条件
A4	300	400	mcd	IF=20mA
A5	400	500		
A6	500	700		
A7	700	900		

电压分档

：

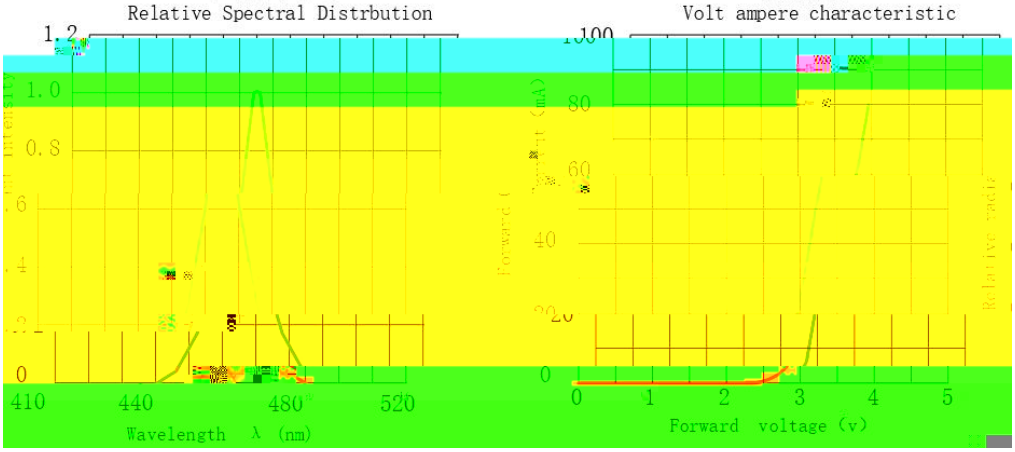
代码	最小值	最大值	单位	测试条件
N13-3	2.8	3.0	V	IF=20mA
N13-4	3.0	3.2		
N13-5	3.2	3.4		

波长分档

代码	最小值	最大值	单位	测试条件
HB04	460	465	nm	IF=20mA
HB05	465	470		
HB06	470	475		

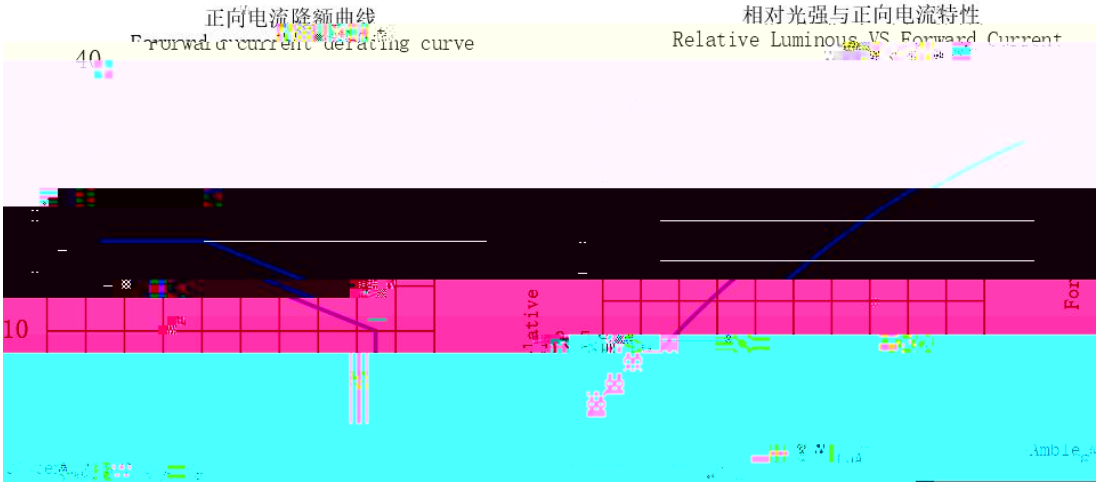
典型特性曲线

光谱分布曲线
Relative Spectral Distrbution



伏安特性
Volt ampere characteristic

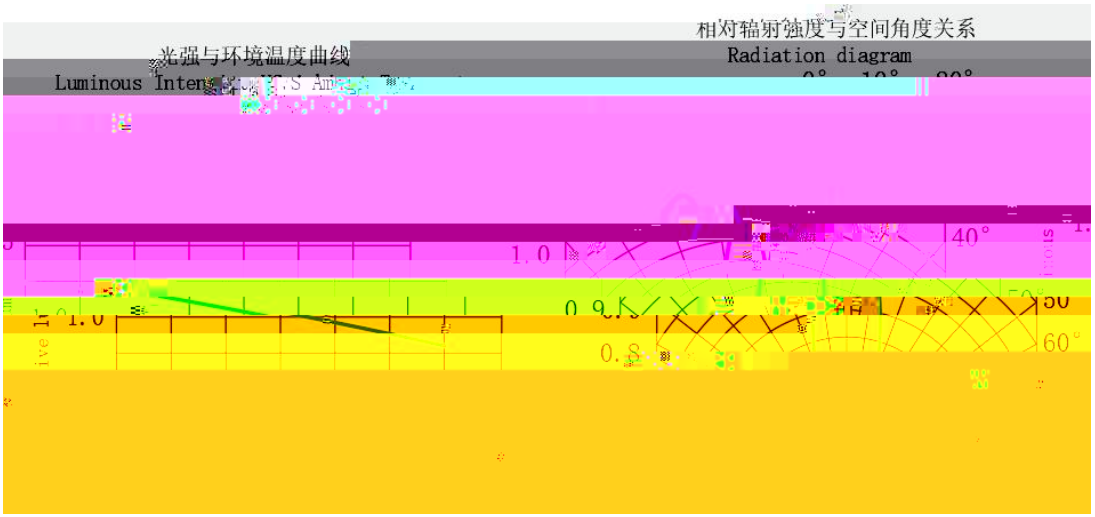
正向电流降额曲线
Forward current derating curve



相对光强与正向电流特性
Relative Luminous VS Forward Current

光强与环境温度曲线
Luminous Intens

相对辐射强度与空间角度关系
Radiation diagram



25±5 /Note If not otherwise indicated the test environment temp erature is 25±5

可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Qty	Fail qty

外形尺寸

包装

*
In Bags

*
Moisture Proof and Anti-Electrostatic Foil Bag

使用注意事项（ ）

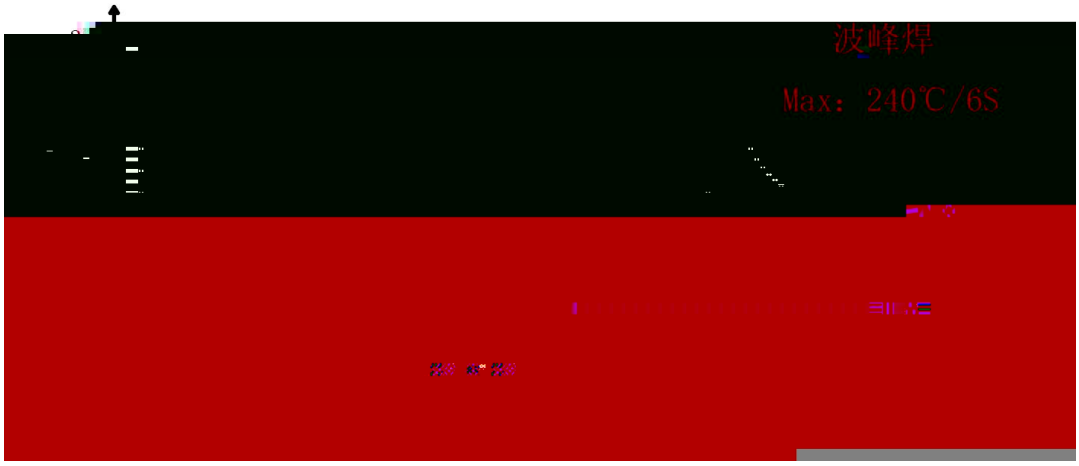
1.
LED

This LED can be used in some ordinary electronic equipment, such as office equipment, communication equipment, house decoration, if BED is used in some high reliability requirements, such as air transportation, traffic control and medical treatment equipment, must refer to the information provided by sales.

使用注意事项（ ）

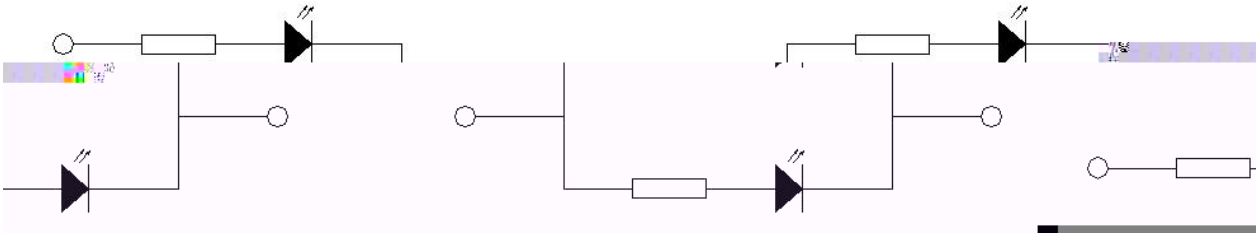
2mm

When welding, welding must be conducted below 2mm of colloid bottom. When welding, try to avoid soaking LED colloid. After welding, avoid adding external force on the pin or shaking LED colloid.



LED LED A LED LED

In the current driving mode of LED, if LED is multiple in parallel, it is recommended to use line A and add a flow limit resistance to each LED to ensure the consistent brightness of LED.



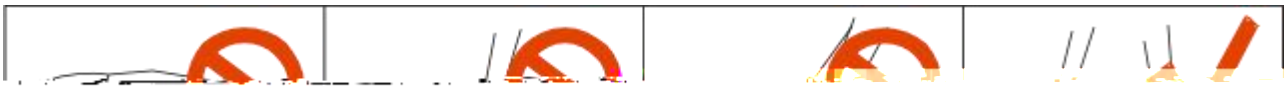
LED InGaN
HBM<1000V <100V

High increase of static electricity and current will damage LED. Use antistatic devices such as protective belts and gloves. Note: human discharge mode HBM <1000V; machine discharge mode <100V.

使用注意事项（ ）

8、其他事项：

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

9、眼睛保护忠告：

LED LED

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity, will cause great hazard to human eyes. Please be careful.

If there are any modifications to the